

#### 30V N-Channel MOSFET

## **General Description**

The 05N03 uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

# Absolute Maximum Ratings

# **Product Summary**

BVDSS	RDSON	N ID	
30V	5mΩ	80A	

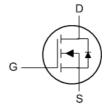
#### **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

# TO-252/251 Pin Configuration







Туре	Package	Marking
CMD05N03	TO-252	CMD05N03
CMU05N03	TO-251	CMU05N03

Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	30	V	
$V_{GS}$	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current <sup>1</sup>	80	Α	
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current <sup>1</sup>	55	Α	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	240	Α	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	180	mJ	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation	90	W	
T <sub>STG</sub>	Storage Temperature Range -55 to 175		°C	
TJ	Operating Junction Temperature Range	-55 to 175	°C	

### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>		62	°C/W
R <sub>eJC</sub>	Thermal Resistance Junction -Case <sup>1</sup>		2.8	°C/W

# CMD05N03/CMU05N03



#### **30V N-Channel MOSFET**

# Electrical Characteristics (T<sub>J</sub>=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
D	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =25A			5	mΩ
R <sub>DS(ON)</sub>		V <sub>GS</sub> =4.5V , I <sub>D</sub> =20A			7.5	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	1		2.5	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25 °C			1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> = ± 20V, V <sub>DS</sub> =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A		22		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2.9		Ω
Qg	Total Gate Charge			50		
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =25V , V <sub>GS</sub> =10V, I <sub>D</sub> =14A		3		nC
$Q_gd$	Gate-Drain Charge			20		
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{DS}=15V , V_{GS}=10V , R_{L}=0.75\Omega$ $R_{GEN}=3\Omega$		12		
T <sub>r</sub>	Rise Time			35		
T <sub>d(off)</sub>	Turn-Off Delay Time			50		ns
T <sub>f</sub>	Fall Time			13		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0V , f=1MHz		1500		
C <sub>oss</sub>	Output Capacitance			220		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			155		

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			80	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2</sup>				240	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =28 A , T <sub>J</sub> =25 ℃			1.2	V

#### Note:

1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width  $\,\leq\,300\text{us}$  , duty cycle  $\,\leq\,2\%$ 

3. The EAS data shows Max. rating . The test condition is  $V_{DD}$  = 20V,  $V_{GS}$  = 10V, L=0.5mH,  $I_{AS}$  = 27A

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